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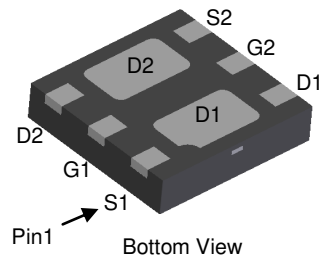
Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
30V	40mΩ @ V _{GS} = 4.5V	5.0A
	75mΩ @ V _{GS} = 2.5V	3.6A

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Battery Charging
- Power Management Functions
- DC-DC Converters
- Portable Power Adaptors

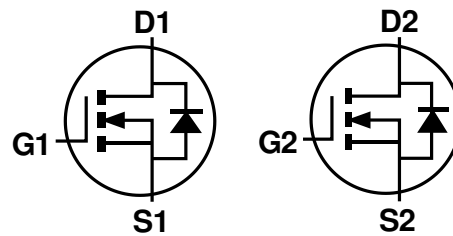


Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: U-DFN2020-6 (Type B)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.0065 grams (Approximate)



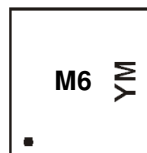
Internal Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN3055LFDB -7	U-DFN2020-6 (Type B)	3,000/Tape & Reel
DMN3055LFDB -13	U-DFN2020-6 (Type B)	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



M6 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: E = 2017)
 M = Month (ex: 9 = September)

Date Code Key

Year	2016	2017	2018	2019	2020	2021	2022	2023
Code	D	E	F	G	H	I	J	K

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	30	V	
Gate-Source Voltage	V_{GSS}	± 12	V	
Continuous Drain Current (Note 6) $V_{GS} = 4.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$	5.0	A
		$T_A = +70^\circ\text{C}$	4.0	A
Maximum Continuous Body Diode Forward Current (Note 6)	I_S	1.5	A	
Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%)	I_{DM}	25	A	
Avalanche Current (Note 7) $L = 0.1\text{mH}$	I_{AS}	11	A	
Avalanche Energy (Note 7) $L = 0.1\text{mH}$	E_{AS}	6	mJ	

Thermal Characteristics

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	P_D	$T_A = +25^\circ\text{C}$	0.81	W
		$T_A = +70^\circ\text{C}$	0.52	
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	Steady State	132	$^\circ\text{C/W}$
		$t < 10\text{s}$	101	
Total Power Dissipation (Note 6)	P_D	$T_A = +25^\circ\text{C}$	1.36	W
		$T_A = +70^\circ\text{C}$	0.87	
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	Steady State	83	$^\circ\text{C/W}$
		$t < 10\text{s}$	60	
Thermal Resistance, Junction to Case (Note 6)	$R_{\theta JC}$	10		
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$	

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV_{DSS}	30	-	-	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current, $T_J = +25^\circ\text{C}$	I_{DSS}	-	-	1.0	μA	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	-	-	± 100	nA	$V_{GS} = \pm 12\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(TH)}$	0.5	-	1.5	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	-	32	40	m Ω	$V_{GS} = 4.5\text{V}, I_D = 3\text{A}$
		-	52	75		$V_{GS} = 2.5\text{V}, I_D = 2\text{A}$
Diode Forward Voltage	V_{SD}	-	0.8	1.2	V	$V_{GS} = 0\text{V}, I_S = 2\text{A}$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C_{iss}	-	458	-	pF	$V_{DS} = 15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	-	50	-	pF	
Reverse Transfer Capacitance	C_{rss}	-	44	-	pF	
Gate Resistance	R_g	-	2.1	-	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge ($V_{GS} = 10\text{V}$)	Q_g	-	11.2	-	nC	
Total Gate Charge ($V_{GS} = 4.5\text{V}$)	$Q_{g4.5}$	-	5.3	-	nC	
Gate-Source Charge	Q_{gs}	-	1.1	-	nC	
Gate-Drain Charge	Q_{gd}	-	1.8	-	nC	$V_{DS} = 15\text{V}, I_D = 4\text{A}$
Turn-On Delay Time	$t_{D(ON)}$	-	1.8	-	ns	
Turn-On Rise Time	t_R	-	2.6	-	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	-	9.5	-	ns	
Turn-Off Fall Time	t_F	-	2.1	-	ns	
Reverse Recovery Time	t_{RR}	-	7.0	-	ns	$I_F = 3\text{A}, di/dt = 100\text{A}/\mu\text{s}$
Reverse Recovery Charge	Q_{RR}	-	1.8	-	nC	

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 - I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^\circ\text{C}$.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.

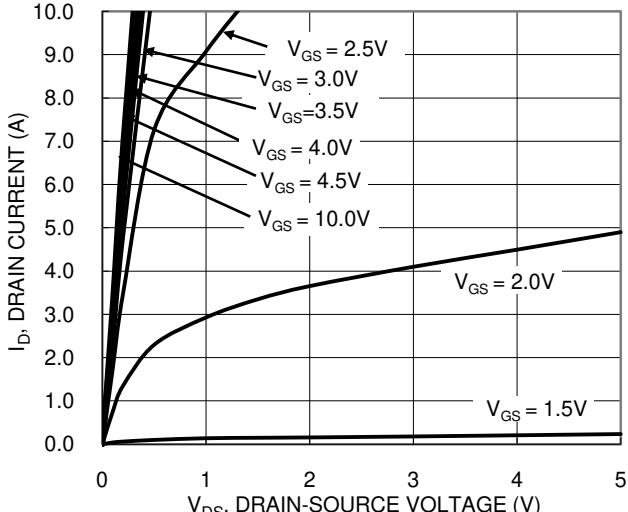


Figure 1. Typical Output Characteristic

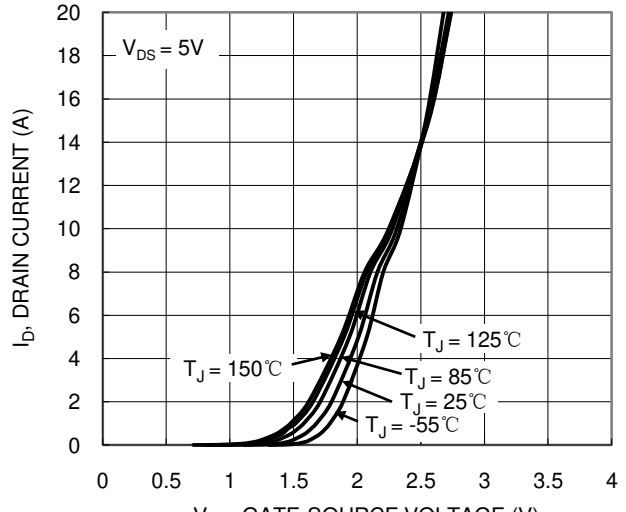


Figure 2. Typical Transfer Characteristic

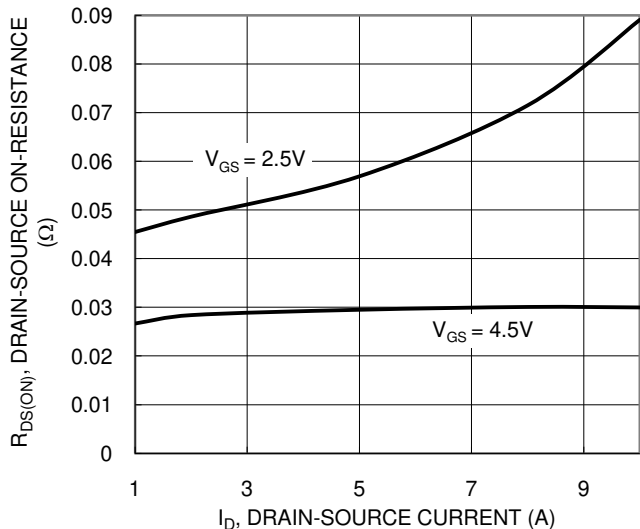


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

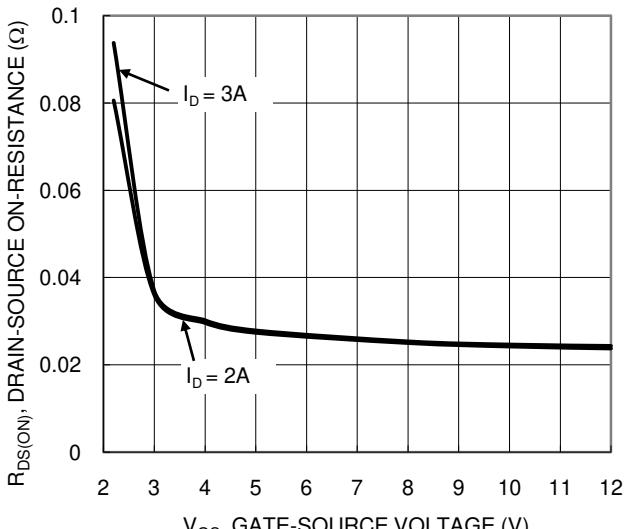


Figure 4. Typical Transfer Characteristic

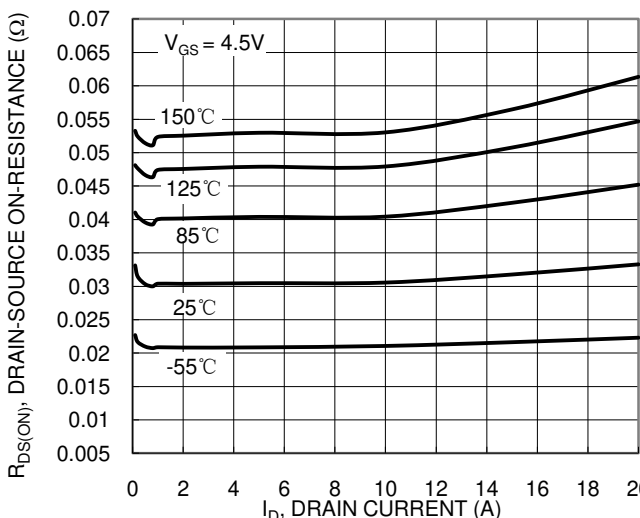


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

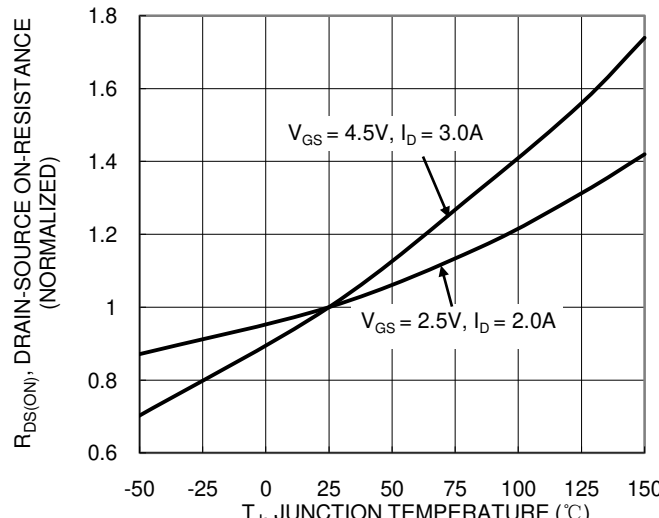


Figure 6. On-Resistance Variation with Temperature

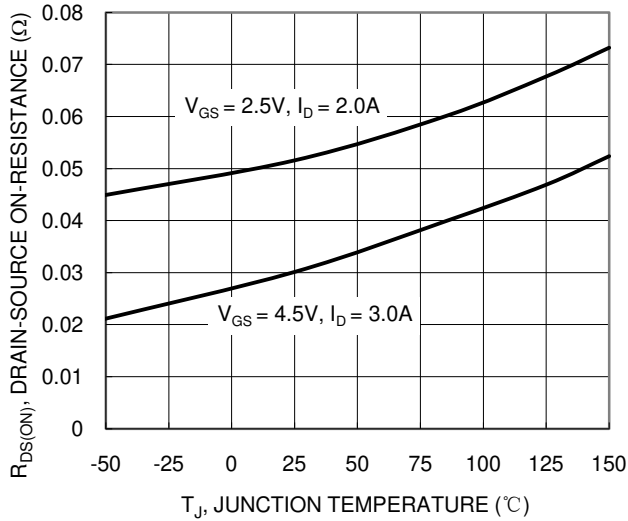


Figure 7. On-Resistance Variation with Temperature

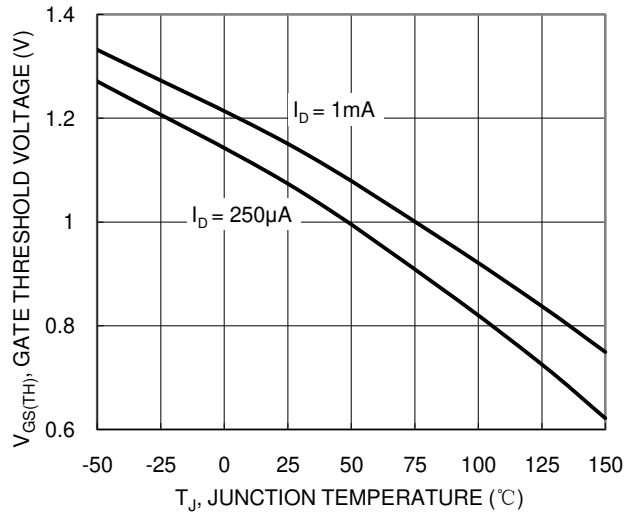


Figure 8. Gate Threshold Variation vs. Junction Temperature

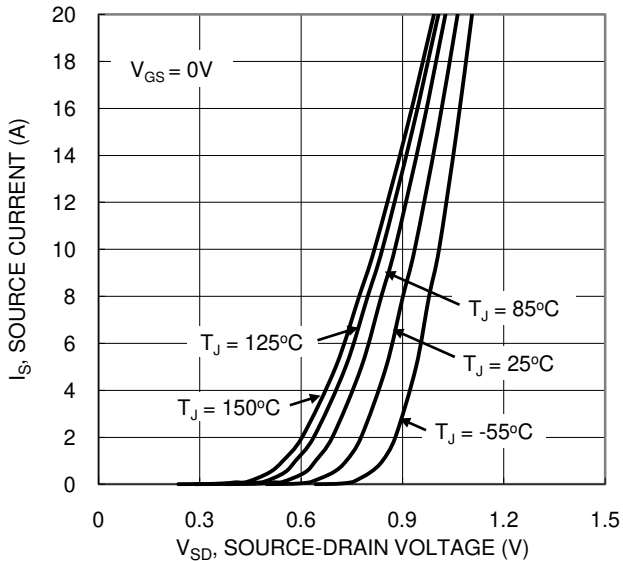


Figure 9. Diode Forward Voltage vs. Current

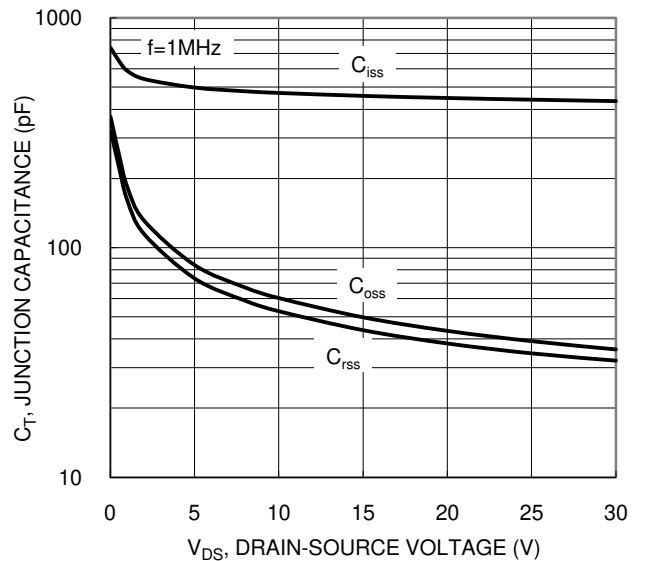


Figure 10. Typical Junction Capacitance

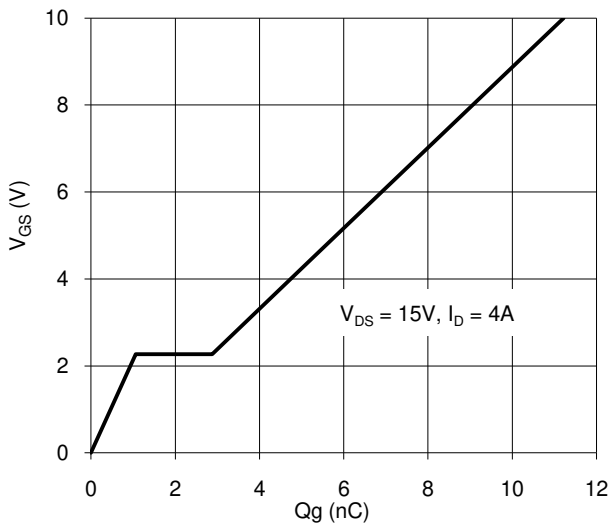


Figure 11. Gate Charge

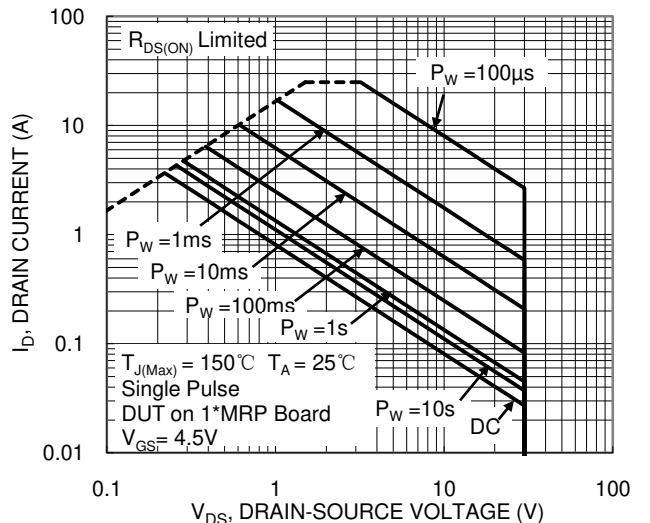


Figure 12. SOA, Safe Operation Area

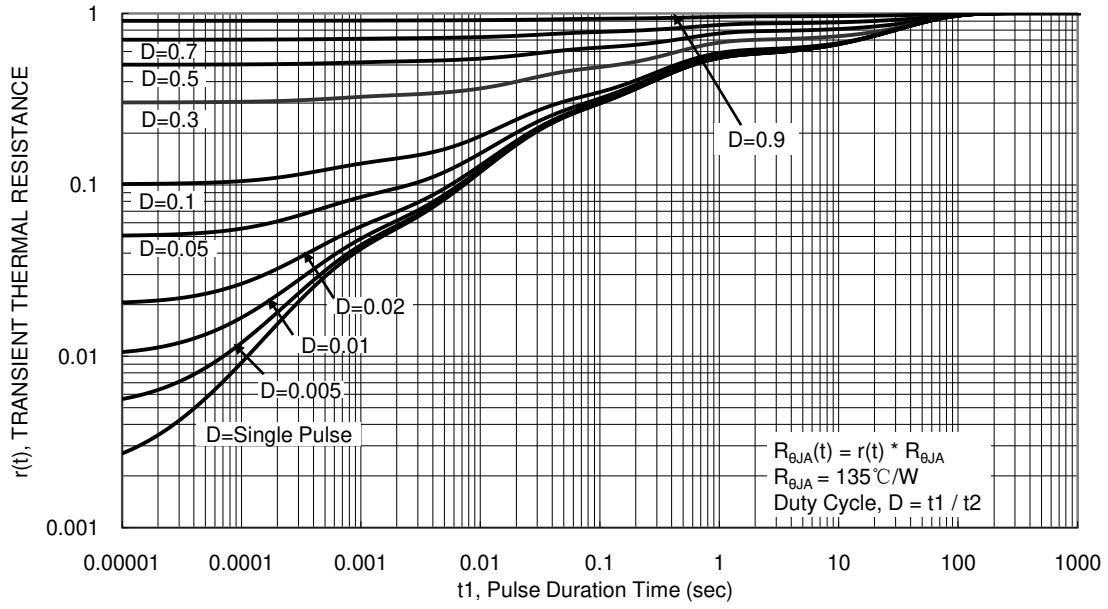
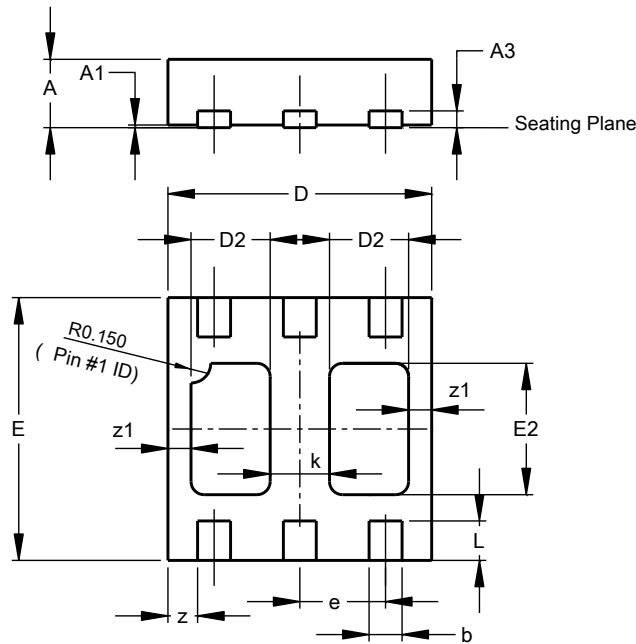


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-6 (Type B)

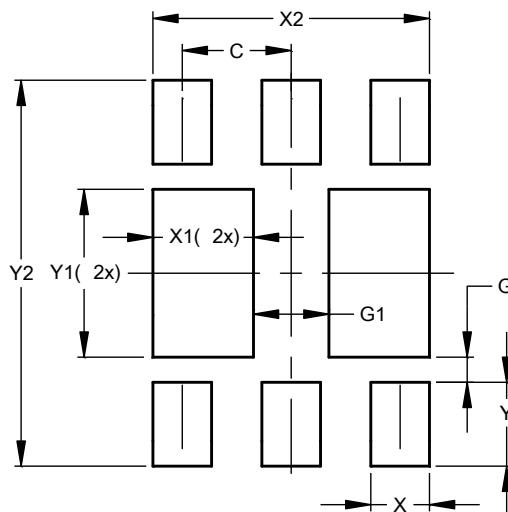


U-DFN2020-6 (Type B)			
Dim	Min	Max	Typ
A	0.545	0.605	0.575
A1	0.00	0.05	0.02
A3	-	-	0.13
b	0.20	0.30	0.25
D	1.95	2.075	2.00
D2	0.50	0.70	0.60
e	-	-	0.65
E	1.95	2.075	2.00
E2	0.90	1.10	1.00
k	-	-	0.45
L	0.25	0.35	0.30
z	-	-	0.225
z1	-	-	0.175
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-6 (Type B)



Dimensions	Value (in mm)
C	0.650
G	0.150
G1	0.450
X	0.350
X1	0.600
X2	1.650
Y	0.500
Y1	1.000
Y2	2.300

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